



TO-252 物料成分表

Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition		CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English			
Die	3	Si		7440-21-3	100.00%
Lead Frame	168	Cu		7440-50-08	99.81%
		Fe		7439-89-6	0.15%
		P		7723-14-0	0.04%
Solder	3	Pb		7439-92-1	95.50%
		Sn		7440-31-5	2.00%
		Ag		7440-22-4	2.50%
Wire	2	Al		7429-90-5	99.99%
		The others		/	0.01%
		Cu		7440-50-08	≥99.99%
Mold Compound	131	Epoxy ResinA		Trade secret	1~5%
		Epoxy ResinB		29690-82-2	1~5%
		Phenol Resin		Trade secret	1~5%
		Silica(aAmorphous)A		60676-86-0	70~90%
		Silica(Amorphous)B		7631-86-9	1~5%
		Carbon Black		1333-86-4	0.1~1%
Plating	3	Tin		7440-31-5	≥99.99%
Total	310				

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied. Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.